

POM copolymer injection molding grade with medium flow and reduced emissions especially for automotive interior application. Good properties as high rigidity, hardness and toughness; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. Burning rate ISO 3795 and FMVSS 302 < 75 mm/min for a thickness more than 1 mm. VDA 275 Emissions < 10 ppm Ranges of applications: automotive engineering, FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information			
Resin Identification Part Marking Code	POM >POM<		ISO 1043 ISO 11469
Rheological properties			
Melt volume-flow rate Temperature Load Moulding shrinkage, parallel	8 190 2.16 2.0 <sup>[1]</sup>	kg	ISO 1133 ISO 294-4, 2577
Moulding shrinkage, normal [1]: @ 195°C	1.9 <sup>[1]</sup>	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus Tensile stress at yield, 50mm/min Tensile strain at yield, 50mm/min Nominal strain at break Flexural modulus Flexural strength Tensile creep modulus, 1h Tensile creep modulus, 1000h Charpy impact strength, 23°C Charpy impact strength, -30°C Charpy notched impact strength, 23°C Charpy notched impact strength, -30°C Ball indentation hardness, H 358/30 Poisson's ratio [P]: Partial Break [C]: Calculated	9 30 2700 89 2500 1300 220 <sup>[P]</sup> 220 6.5 6	MPa % MPa MPa MPa	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 178 ISO 899-1 ISO 179/1eU ISO 179/1eU ISO 179/1eA ISO 179/1eA ISO 2039-1
Thermal properties			
Melting temperature, 10°C/min Temperature of deflection under load, 1.8 MPa Coefficient of linear thermal expansion (CLTE), parallel	166 104 110		ISO 11357-1/-3 ISO 75-1/-2 ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal		E-6/K	ISO 11359-1/-2
Thermal conductivity of melt Effective thermal diffusivity, flow Specific heat capacity of melt	4.85E-8	W/(m K) m²/s J/(kg K)	ISO 22007-2 ISO 22007-4 ISO 22007-4

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Relative permittivity, 1MHz4IEC 62631-2-1Dissipation factor, 100Hz20E-4IEC 62631-2-1Dissipation factor, 1MHz50E-4IEC 62631-2-1Volume resistivity1E12Ohm.mIEC 62631-3-1Surface resistivity1E14OhmIEC 62631-3-2Electric strength35kV/mmIEC 60243-1Comparative tracking index600IEC 60112Physical/Other propertiesHumidity absorption, 2mm0.2 %Sim. to ISO 62Water absorption, 2mm0.65 %Sim. to ISO 62Density1410kg/m³ISO 1183InjectionDrying RecommendednoDrying Temperature100 °CDrying Time, Dehumidified Dryer3 - 4 hProcessing Moisture Content≤0.2 %Melt Temperature Optimum200 °CMin. melt temperature190 °C
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Min. melt temperature 190 °C
Max. melt temperature 210 °C
Screw tangential speed ≤0.3 m/s
Mold Temperature Optimum 100 °C
Min. mould temperature 80 °C
Max. mould temperature 120 °C
Hold pressure range 60 - 120 MPa
Back pressure 4 MPa
Ejection temperature 140 °C

### **Characteristics**

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low emissions

### Additional information

Injection molding

#### Preprocessing

To achive low emission values pre drying using a recirculating air dryer (100 to 120  $^{\circ}$ C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,1 %

### Processing

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Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

### Postprocessing

Conditioning e.g. moisturizing is not necessary.

#### **Processing Notes**

#### Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granul

#### Storage

The product can then be stored in standard conditions until processed.

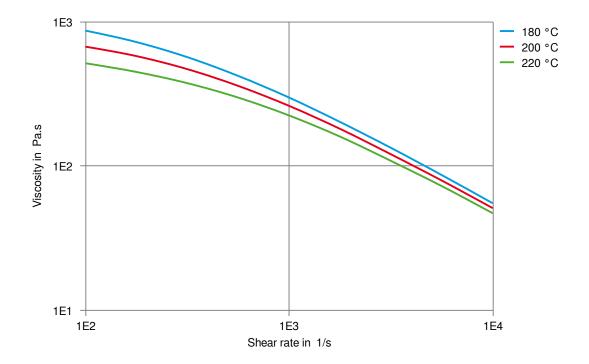
#### Automotive

OEM General Motors General Motors STANDARD GMW22P-POM-C2 GMW22P-POM-C2 ADDITIONAL INFORMATION Black Natural





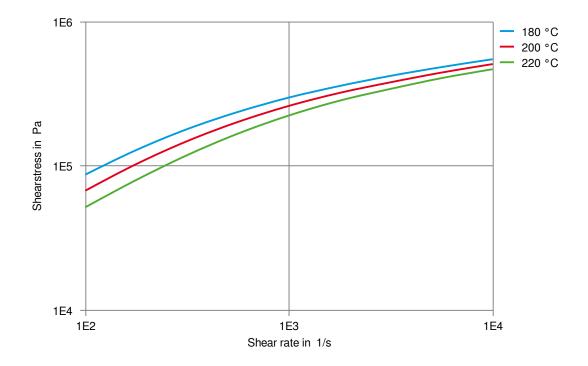
Viscosity-shear rate





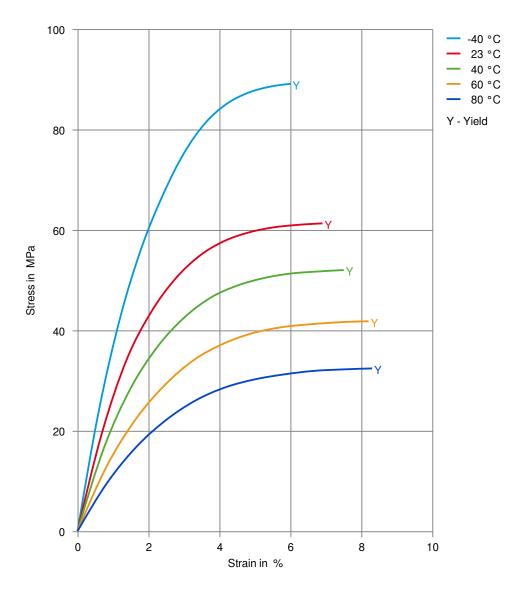


#### Shearstress-shear rate



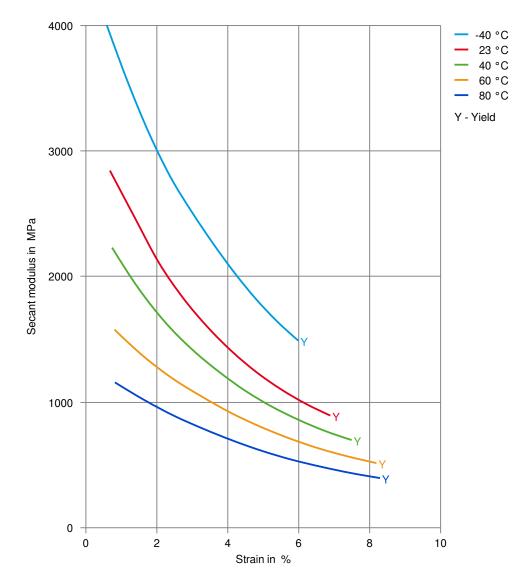


Stress-strain



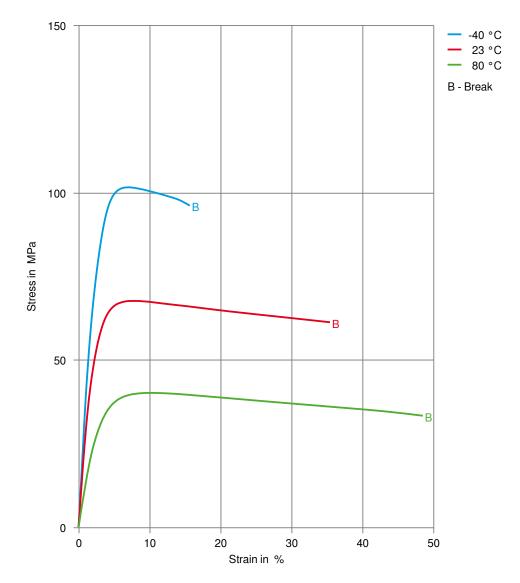


### Secant modulus-strain





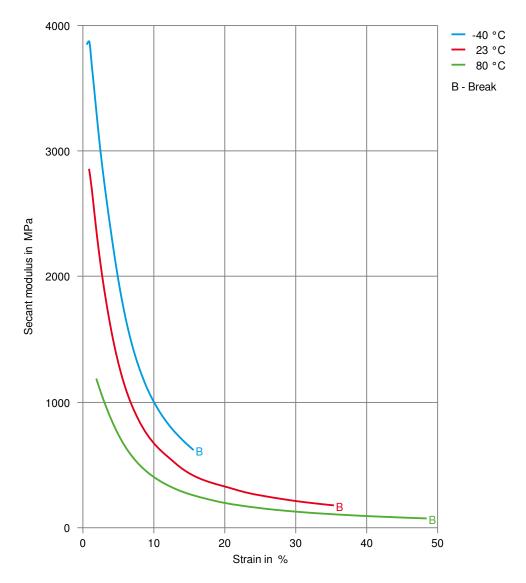
### Stress-strain, 50mm/min





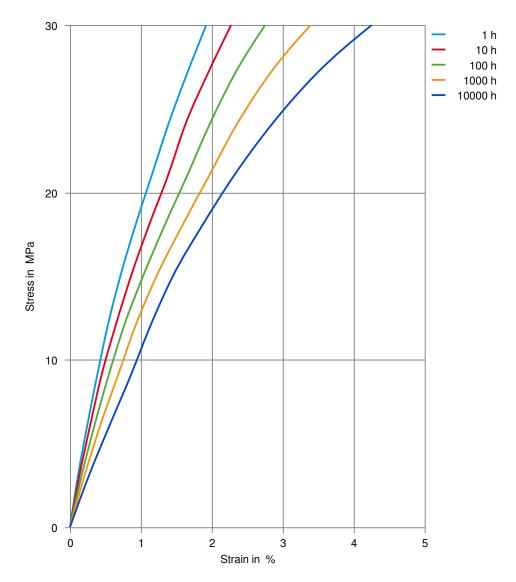


### Secant modulus-strain, 50mm/min





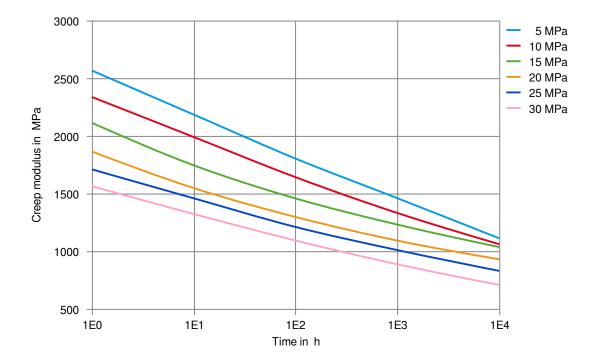
### Stress-strain (isochronous) 23°C







Creep modulus-time 23°C



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NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication as a promise or guarantee of specific properties of our groucts. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material mentioned in this publication should satisfy themselves that they can meet all applicable safety and health standards. We strongly recommend that users seek and adhere to the

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